



HSEC8-120-01-L-DV-A-PE



HSEC8-110-01-L-DV-A-PE

HSEC8-PE SERIES

(0.80 mm) .0315"

PASS-THROUGH EDGE RATE® CARD SOCKET

SPECIFICATIONS

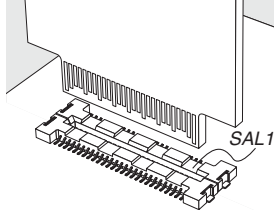
For complete specifications and recommended PCB layouts see www.samtec.com?HSEC8

Insulator Material:
Black Liquid Crystal Polymer
Contact:
BeCu
Plating:
Au or Sn over 50 μm (1.27 μm) Ni
Operating Temp:
-55 °C to +125 °C
RoHS Compliant:
Yes

PROCESSING

Lead-Free Solderable:
Yes
SMT Lead Coplanarity:
(0.10 mm) .004" max (10-20)

OTHER SOLUTIONS



• Other card pass-through options. See SAL1 Series.

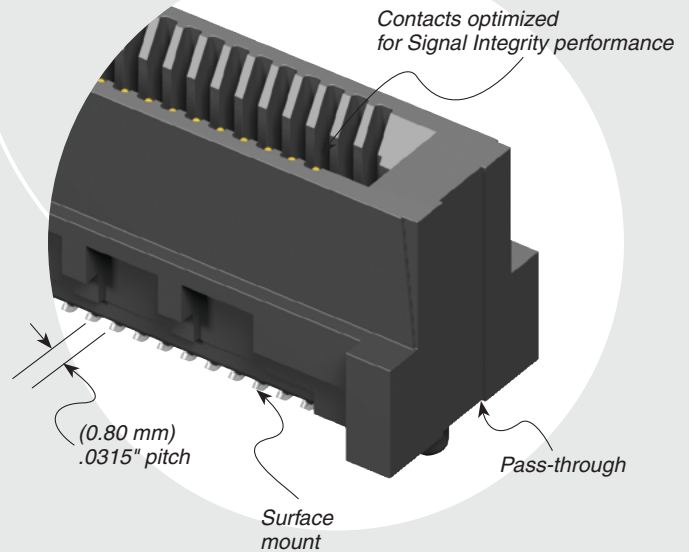
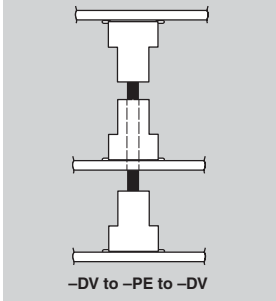
ALSO AVAILABLE (MOQ Required)

• Other platings

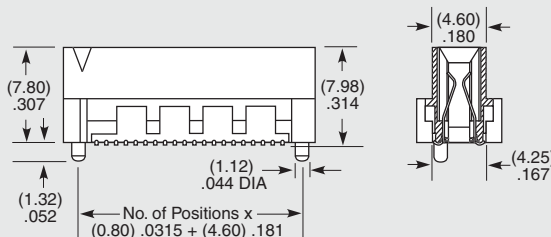
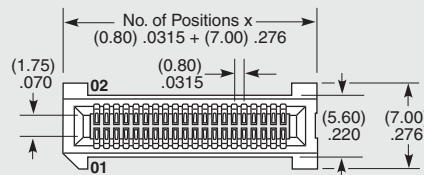
Mates with:
(1.60 mm) .062" thick card, HSC8



BOARD-TO-BOARD APPLICATIONS



HSEC8	1	POSITIONS PER ROW	CARD THICKNESS	PLATING OPTION	DV	A	PE	OTHER OPTION
		10, 13, 20	-01 = (1.60 mm) .062" thick card	-L = 10 μm (0.25 μm) Gold on contact, Matte Tin on tail -S = 30 μm (0.76 μm) Gold on contact, Matte Tin on tail				-K = (5.50 mm) .217" DIA Polyimide Film Pick & Place Pad -TR = Tape & Reel Packaging



Notes:
While optimized for 50 Ω applications, this connector with alternative signal/ground patterns may also perform well in certain 75 Ω applications.

Some lengths, styles and options are non-standard, non-returnable.

Due to technical progress, all designs, specifications and components are subject to change without notice.

WWW.SAMTEC.COM

All parts within this catalog are built to Samtec's specifications. Customer specific requirements must be approved by Samtec and identified in a Samtec customer-specific drawing to apply.